


MATERIAL DATA SHEET



SMD Diodes Specialist

Material #	CDSNC4148	
Product Line	1206	
Date	2009/10/12	
Rev. date	B	

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	Base Material	Ceramic substrate	7.865	Al ₂ O ₃	1344-28-1	>96%	71.07	
2	Silver paste	Silver paste	0.329	Silver	7440-22-4	40~50	2.97	
				Copper(II)oxide	1317-38-0	1~5		
				Diethylene glycol monobutyl ether	112-34-5	15~25		
				Terpineol	8000-41-7	10~20		
3	Conduct paste	Silver paste	0.573	Silver	7440-22-4	70-80%	5.18	
				Diethylene glycol monobutyl ether	112-34-5	10-20%		
4	Dice	Silicon	0.033	Si	7440-21-3	70.90%	0.30	
				Ag	7440-22-4	28.60%		
5	Liquid Encapsulant	Epoxy resin	1.900	Silica	7631-86-9	65-75%	17.17	
				BIS-Phenol type liquid Epoxy	9003-36-5	15-25%		
				Carboxylic acid anhydride	19438-60-9	15-25%		
6	Termination paste	Silver paste	0.164	Silver flake	7440-22-4	55~65%	1.48	
				Epoxy resin	25068-38-6	2~5%		
				Phenoxy resin	26402-79-9	4~5%		
				Phenolic resin	24979-70-2	2~5%		
				Cyclohexanol	108-93-0	12~18%		
				Benzyl alcohol	100-51-6	3~6%		
7	Plating Layer	Tin plating	0.203	Tin	7440-31-5	99.90%	1.83	
			Total weight	11.067				

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